



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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J. W. H.  
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In re Patent Application of: )  
Shinji TAKEDA et al. ) Atty. Docket No.: TM&K0008  
Serial No. 09/785,486 ) Group Art Unit: 2814  
Filed: February 20, 2001 ) Examiner: GRAYBILL, D.  
For: SEMICONDUCTOR DEVICE AND ) Date: June 19, 2002  
PROCESS FOR FABRICATION )  
THEREOF )

**AMENDMENT (B)**

**Box: Fee Amendment**  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the official Office Action dated December 19, 2001, please amend the application identified above as follows:

**IN THE CLAIMS:**

Kindly amend claims 17-22, 40 and 43 as follows:

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17. (Amended) A material comprising an organic die-bonding film having a peel strength of 0.5 kgf/(5 mm x 5 mm chip) or higher when a semiconductor has been bonded to a support member with said material under conditions of 100-230°C temperature and pressure of 0.1-30 gf/mm<sup>2</sup>.

18. (Amended) A material comprising an organic die-bonding film having the property of bonding a semiconductor chip to a support member under conditions of 100-230°C temperature